

Paragon Communications collaborates with Intel on WiMAX products

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Paragon Communications Ltd. announced today that it is collaborating with Intel Corporation on technology that will help increase output power and hence range and reduce power consumption and heat dissipation of power amplifiers in WiMAX technologies.

As part of the collaboration, Intel plans to use Paragon's XNN® technology in its WiMAX products. Paragon's XNN® (eXcess eNvelope eNhancement) is an advanced technology that provides dramatic improvement in efficiency and RF output of Power Amplifiers.

"Intel's plan to incorporate our PA enhancement technology in its products is a step forward in our demonstrations of the benefits that XNN® brings to mobile devices in terms of increased output power and hence range, reduced power consumption, longer battery life", commented Prof. Israel Bar-David, Co-Founder of Paragon

"Power efficiency and increased output power are critical for enabling mobile wireless technology, and Intel is pleased we could make strides in these key areas with Paragon," said Scott Richardson, general manager of Intel's Broadband Wireless Division.

Paragon's Chairman, Dr. Eli Plotnik "Our goal is to become the industry standard for enhanced PA's for WiMAX and Wi-Fi products as well as for MIMO based wireless systems.

About Paragon

Paragon Communications Ltd. provides solutions for enhancing performance of wireless power amplifiers and systems. Paragon offers its XNN® technology that enhances output power, efficiency and simultaneously reduces power consumption and heat dissipation in Wi-Fi, WiMAX and other wireless systems.

Paragon's customers include leading companies such as Samsung and Remec Inc. and other wireless vendors.

Paragon holds many patents for enhancement of PA's and wireless systems performance.

For further information please visit our Website at www.paragon-communications.com